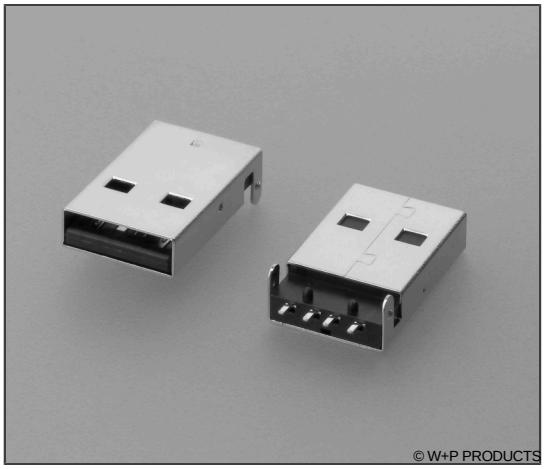
# 8230

## SMT-USB Steckverbinder, Typ A, Stecker liegend

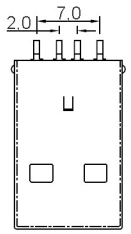
### *SMT USB Connectors, Type A, Plug Horizontal*

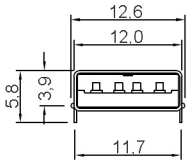
**Technische Daten / *Technical Data***

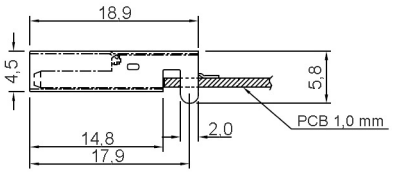
| | |
|---|---|
| Gehäuse | Messing, verzinnt/vernickelt |
| *Shell* | *Tin/nickel plated brass* |
| Isolierkörper | Thermoplast, nach UL94 V-0 |
| *Insulator* | *Thermoplastic, rated UL94 V-0* |
| Kontaktmaterial | Kupferlegierung |
| *Contact Material* | *Copper alloy* |
| Kontaktoberfläche | Gold über Nickel (siehe Optionen unten) |
| *Contact Surface* | *Gold over nickel (see options below)* |
| Oberfläche Lötanschluss | Zinn über Nickel |
| *Plating Solder Side* | *Tin plated over nickel* |
| Durchgangswiderstand | < 30 mΩ |
| *Contact Resistance* | *< 30 mΩ* |
| Isolationswiderstand | > 1000 MΩ |
| *Insulation Resistance* | *> 1000 MΩ* |
| Spannungsfestigkeit | 500 V AC |
| *Test Voltage* | *500 V AC* |
| Nennspannung | 30 V RMS |
| *Voltage Rating* | *30 V RMS* |
| Nennstrom | 1,5 A bei 25°C |
| *Current Rating* | *1,5 A at 25°C* |
| Temperaturbereich | -55 °C ... +85 °C |
| *Temperature Range* | *-55 °C ... +85 °C* |
| Verarbeitung | Reflow-Lötverfahren |
| *Processing* | *Reflow soldering* |

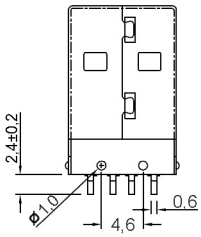


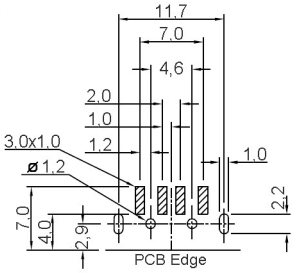

Weitere Farben auf Anfrage
*More colour options on request*




**PCB Layout**

| *Series* | *Colour** | *Plating** | *Package* |
|---|---|---|---|
| **8230** | **30** | **60** | **00** |
| | **10** Schwarz<br>*Black*<br>**30** Weiß<br>*White* | **60** Sel. Au/Sn<br>**80** Sel. Au 0,75µm/Sn (USB 2.0) | **00** Schüttgut<br>*Bulk goods* |

* Dies ist ein **Bestellbeispiel** -
bitte durch Ihre Spezifikationen ersetzen.
** This is an **order example** -*
*please replace by your specifications.*

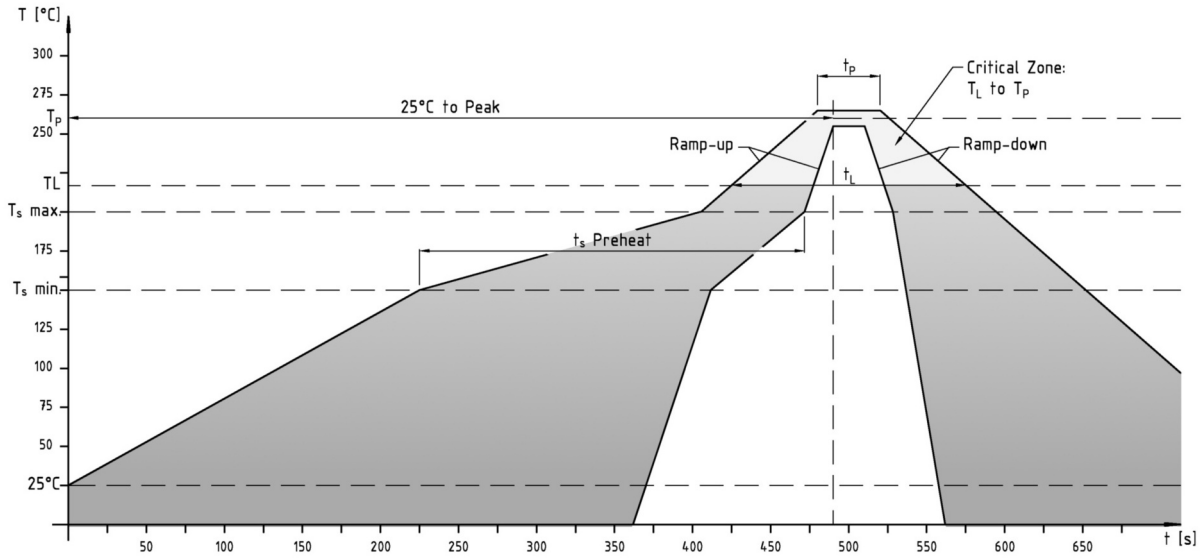
# Informationen zum Reflow-Lötverfahren
## *Reflow Soldering Information*

### Reflow-Lötempfehlung für kurze Lötzeiten

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

| Profileigenschaft | Kennwert |
|---|---|
| Temperatur Minimum $T_S$min | 150 °C |
| Temperatur Maximum $T_S$max | 200 °C |
| Dauer $T_S$min – $T_S$max | 60 – 180s |
| Temperatur Lötbereich $T_L$ | 217 °C |
| Verweildauer oberhalb $T_L$ | 60 – 180s |
| Ramp-Up Rate $T_S$max – $T_P$ | max. 3 °C / s |
| Höchsttemperatur $T_P$ | 260±5 °C |
| Dauer Höchsttemperatur | 20 – 40s |
| Ramp-Down Rate $T_P$max – $T_S$min | 6 °C / s |
| Dauer 25 °C – Höchsttemperatur $T_P$ | max. 8m |

### Reflow Soldering Recommendation For Shorter Peak Times

*Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).*

| *Profile Feature* | Key Values |
|---|---|
| *Minimum Temperature $T_S$min* | *150 °C* |
| *Maximum Temperatur $T_S$max* | *200 °C* |
| *Duration $T_S$min – $T_S$max* | *60 – 180s* |
| *Soldering Range Temperature $T_L$* | *217 °C* |
| *Duration above $T_L$* | *60 – 180s* |
| *Ramp-Up Rate $T_S$max – $T_P$* | *max. 3 °C / s* |
| *Peak Temperature $T_P$* | *260±5 °C* |
| *Duration Peak Temperature* | *20 – 40s* |
| *Ramp-Down Rate $T_P$max – $T_S$min* | *6 °C / s* |
| *Duration 25°C - Peak Temp. $T_P$* | *max. 8min* |